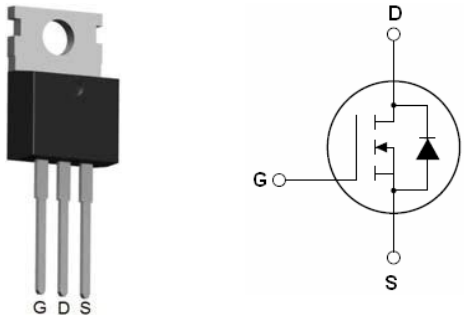
 Lead Free Package and Finish

## N-Channel Trench Power MOSFET

<p><b>General Description</b></p> <p>The RS100N135T is SGT MOSFET designed for high current switching applications. Rugged EAS capability and ultra low <math>R_{DS(ON)}</math> is suitable for PWM, load switching applications.</p> <p><b>Features</b></p> <ul style="list-style-type: none"> <li>● <math>V_{DS}=100V</math>; <math>I_D=135A@ V_{GS}=10V</math>; <math>R_{DS(ON)}&lt;5.8m\Omega @ V_{GS}=10V</math></li> <li>● Ultra Low On-Resistance</li> <li>● High UIS and UIS 100% Test</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>● Hard Switched and High Frequency Circuits</li> <li>● Uninterruptible Power Supply</li> </ul>	 <p><b>To-220 Top View</b>      <b>Schematic Diagram</b></p> <p><math>V_{DS} = 100V</math></p> <p><math>I_D = 135A</math></p> <p><math>R_{DS(ON)} = 4.8m\Omega (Typ.)</math></p>
---	--

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
RS100N135T	RS100N135T	TO-220	-	-	-

**Table 1. Absolute Maximum Ratings (TA=25°C)**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-Source Voltage ( $V_{GS}=0V$ )	100	V
$V_{GS}$	Gate-Source Voltage ( $V_{DS}=0V$ )	$\pm 20$	V
$I_{D(DC)}$	Drain Current (DC) at $T_c=25^\circ C$	135	A
$I_{D(DC)}$	Drain Current (DC) at $T_c=100^\circ C$	105	A
$I_{DM (pluse)}$	Drain Current-Continuous@ Current-Pulsed <b>(Note 1)</b>	540	A
$P_D$	Maximum Power Dissipation( $T_c=25^\circ C$ )	232	W
	Derating Factor	1.55	W/°C
EAS	Single Pulse Avalanche Energy <b>(Note 2)</b>	900	mJ
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 To 175	°C

**Notes** 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2.EAS condition: $T_J=25^\circ C, V_{DD}=40V, V_G=10V, R_G=25\Omega$

**Table 2. Thermal Characteristic**

Symbol	Parameter	Value	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	---	0.646	$^{\circ}C/W$

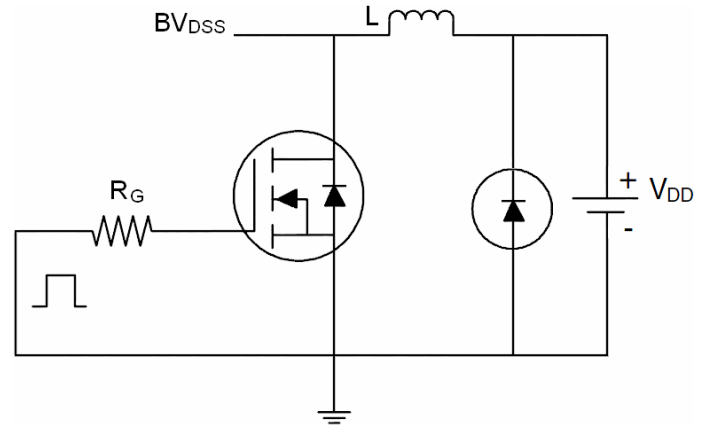
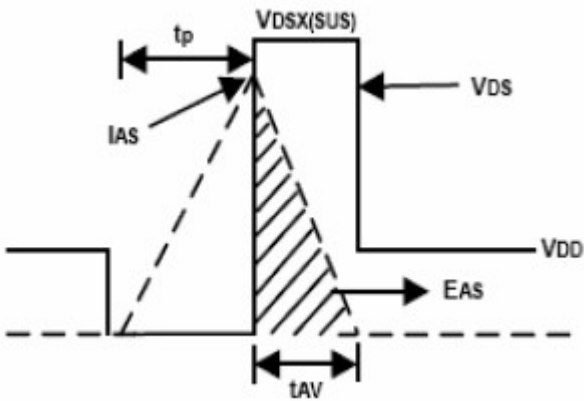
**Table 3. Electrical Characteristics (TA=25 $^{\circ}C$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>On/Off States</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	100			V
$I_{DSS}$	Zero Gate Voltage Drain Current(Tc=25 $^{\circ}C$ )	$V_{DS}=100V, V_{GS}=0V$			1	$\mu A$
$I_{DSS}$	Zero Gate Voltage Drain Current(Tc=125 $^{\circ}C$ )	$V_{DS}=100V, V_{GS}=0V$			10	$\mu A$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2		4	V
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS}=10V, I_D=40A$		4.8	5.8	m $\Omega$
<b>Dynamic Characteristics</b>						
$g_{FS}$	Forward Transconductance	$V_{DS}=10V, I_D=15A$	20			S
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V,$ $f=1.0MHz$		6750		PF
$C_{oss}$	Output Capacitance			1020		PF
$C_{rss}$	Reverse Transfer Capacitance			108		PF
$Q_g$	Total Gate Charge	$V_{DS}=20V, I_D=5A,$ $V_{GS}=10V$		98		nC
$Q_{gs}$	Gate-Source Charge			29		nC
$Q_{gd}$	Gate-Drain Charge			20		nC
<b>Switching Times</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=30V, I_D=40A, R_L=15\Omega$ $V_{GS}=10V, R_G=2.5\Omega$		15		nS
$t_r$	Turn-on Rise Time			32.3		nS
$t_{d(off)}$	Turn-Off Delay Time			24		nS
$t_f$	Turn-Off Fall Time			15		nS
<b>Source-Drain Diode Characteristics</b>						
$I_{SD}$	Source-drain Current(Body Diode)			135		A
$I_{SDM}$	Pulsed Source-Drain Current(Body Diode)			540		A
$V_{SD}$	Forward On Voltage <sup>(Note 1)</sup>	$T_J=25^{\circ}C, I_{SD}=40A, V_{GS}=0V$		0.9	0.99	V
$t_{rr}$	Reverse Recovery Time <sup>(Note 1)</sup>	$T_J=25^{\circ}C, I_F=30A$ $di/dt=100A/\mu s$		45		nS
$Q_{rr}$	Reverse Recovery Charge <sup>(Note 1)</sup>			80		nC
$t_{on}$	Forward Turn-on Time	Intrinsic turn-on time is negligible(turn-on is dominated by $L_S+L_D$ )				

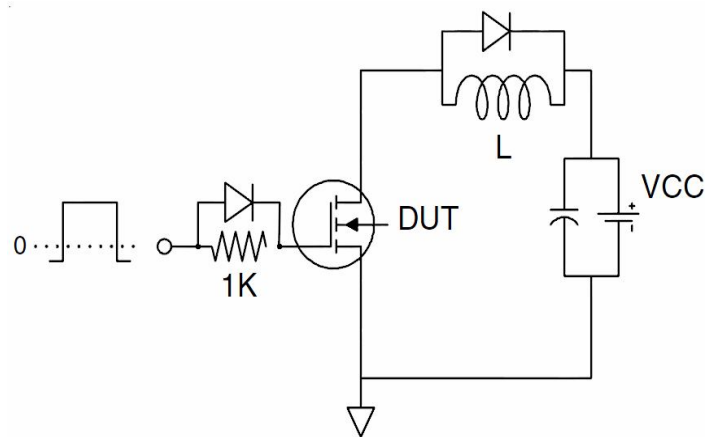
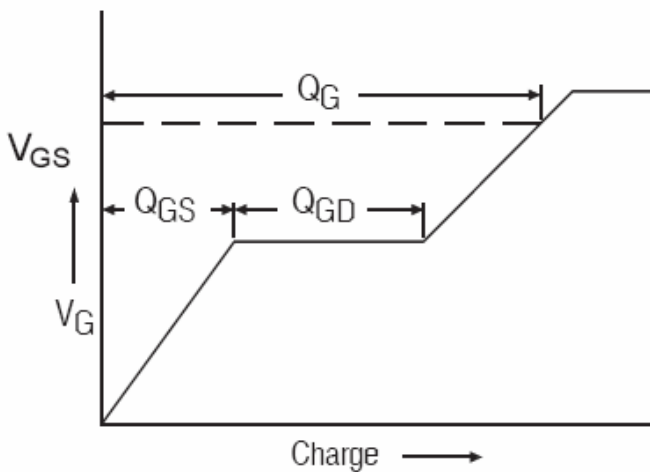
Notes 1. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 1.5\%$ ,  $R_G=25\Omega$ , Starting  $T_J=25^{\circ}C$

## Test Circuit

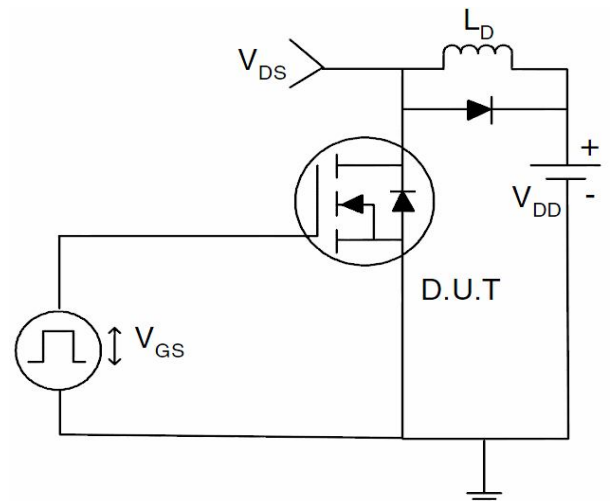
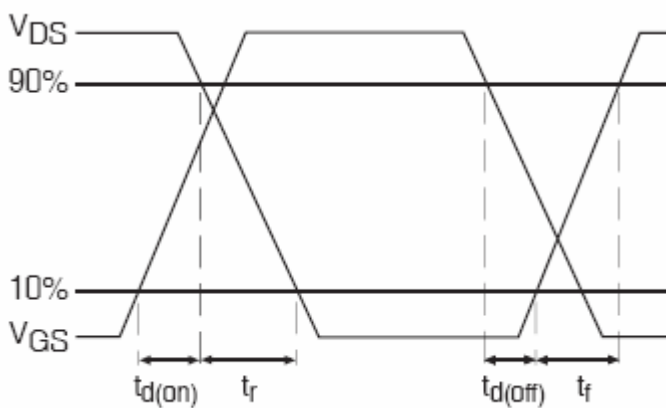
### 1) $E_{AS}$ Test Circuits



### 2) Gate Charge Test Circuit:



### 3) Switch Time Test Circuit:



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

Figure1. Output Characteristics

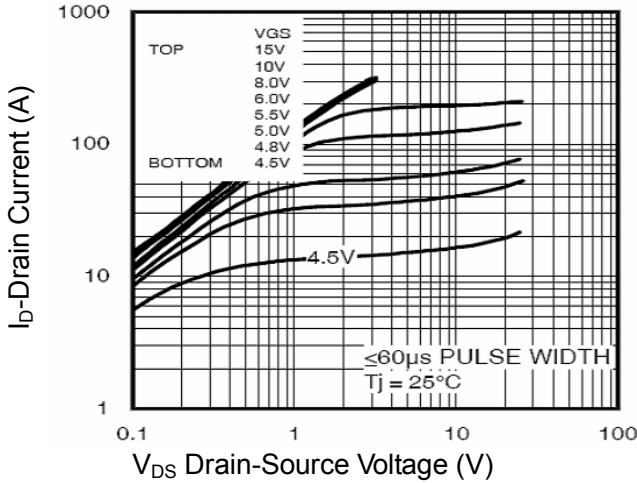


Figure2. Transfer Characteristics

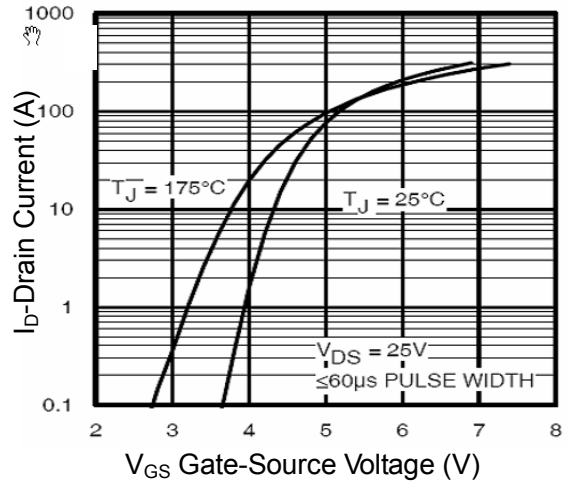


Figure3. BVDSS vs Junction Temperature

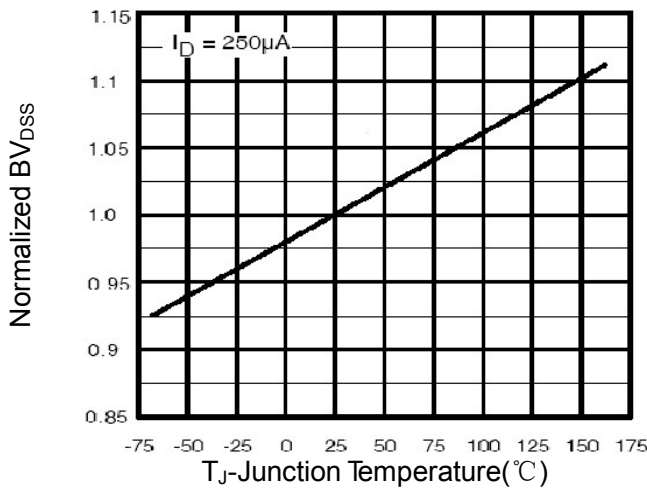


Figure4. ID vs Junction Temperature

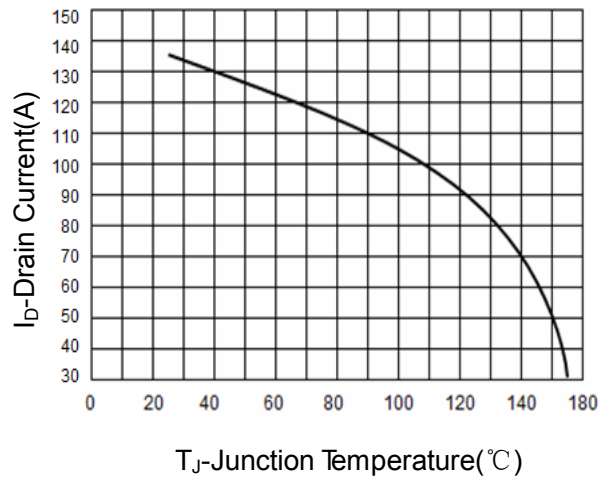


Figure5. VGS(th) vs Junction Temperature

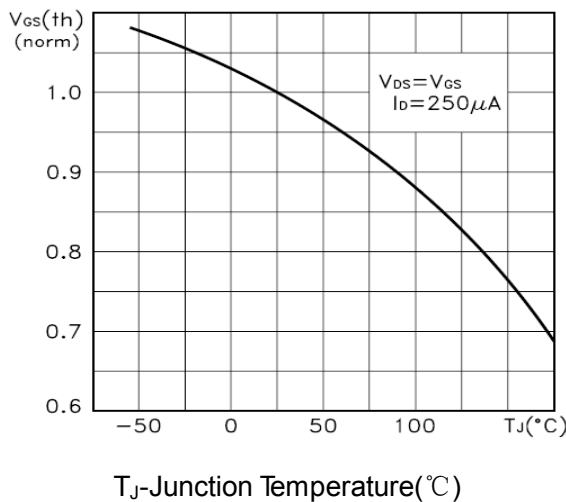


Figure6. Rdson Vs Junction Temperature

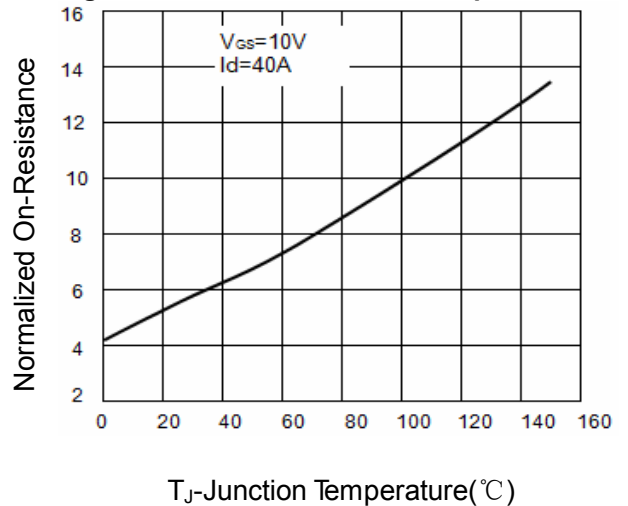


Figure7. Gate Charge

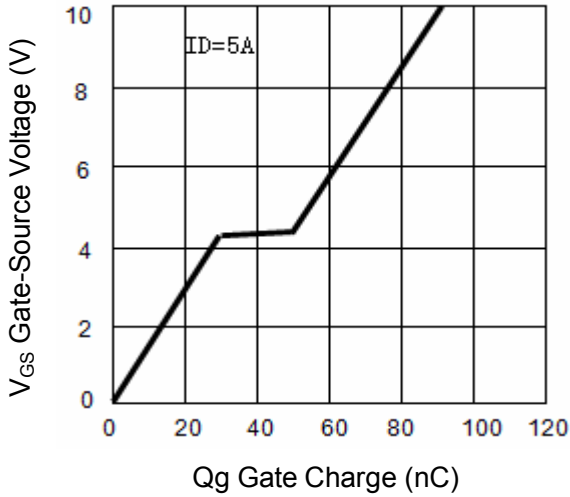


Figure8. Capacitance vs V\_DS

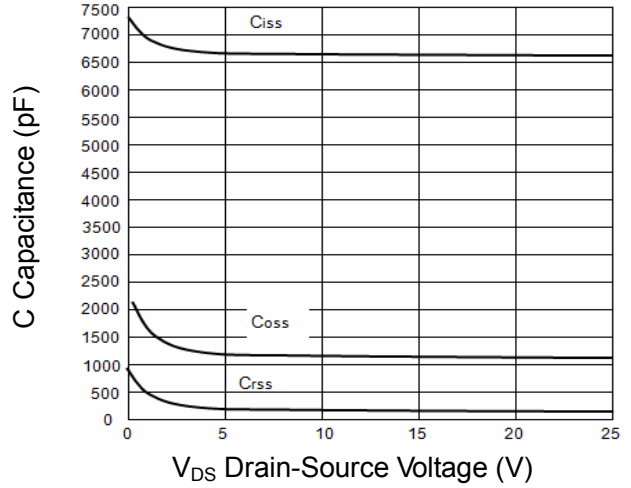


Figure9. Source- Drain Diode Forward

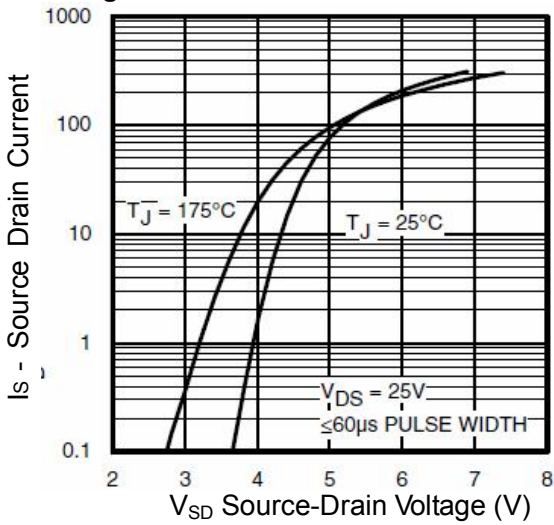


Figure10. Safe Operation Area

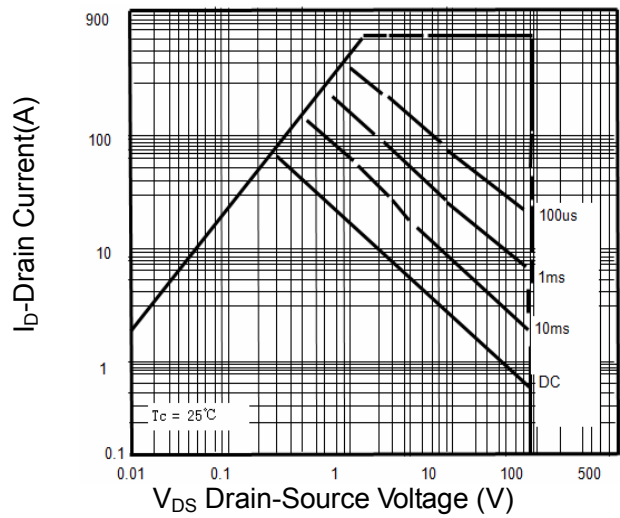
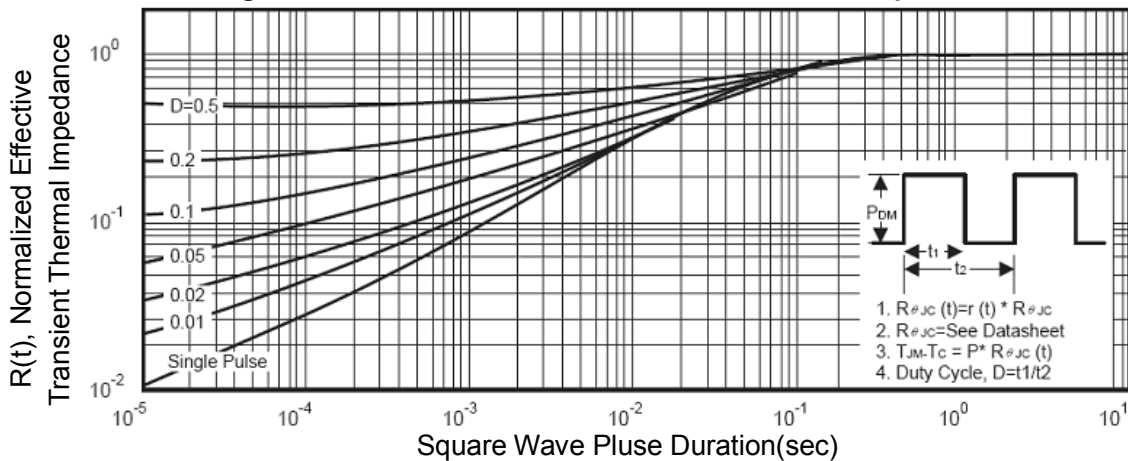
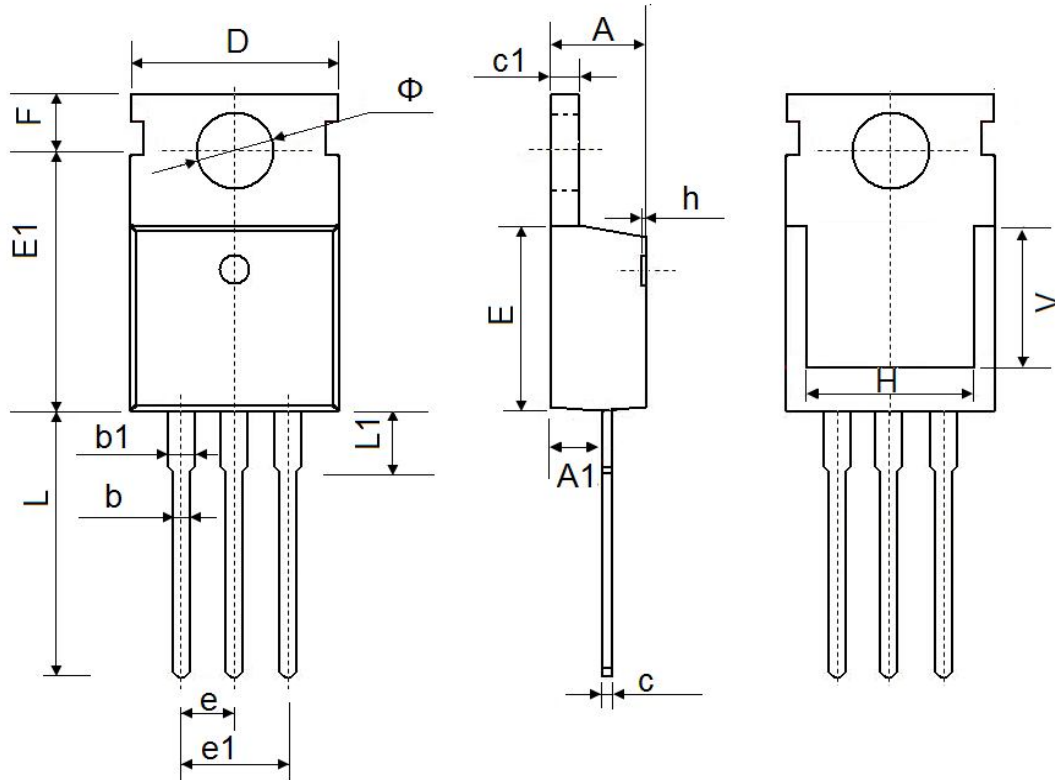


Figure11. Normalized Maximum Transient Thermal Impedance



**TO-220 Package Information**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.300	4.700	0.169	0.185
A1	2.200	2.600	0.087	0.102
b	0.700	0.950	0.028	0.037
b1	1.170	1.410	0.046	0.056
c	0.450	0.650	0.018	0.026
c1	1.200	1.400	0.047	0.055
D	9.600	10.400	0.378	0.409
E	8.8500	9.750	0.348	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.750	14.300	0.502	0.563
L1	2.850	3.950	0.112	0.156
V	7.500 REF.		0.295 REF.	
Φ	3.400	4.000	0.134	0.157